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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

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Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	CANbus, I ² C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I ² S, Motor Control PWM, POR, PWM, WDT
Number of I/O	85
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16К х 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 49x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep128gm710-i-pf

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Pin #	Full Pin Name	Pin #	Full Pin Name
E1	PWM6H/T8CK/RD4	J8	No Connect
E2	PWM6L/T9CK/RD3	J9	No Connect
E3	AN19/RP118/PMA5/RG6	J10	AN41/RP81/RE1
E4	PWM5H/RD2	J11	AN30/SDA1/RPI52/RC4
E5	No Connect	K1	PGED3/OA2IN-/AN2/C2IN1-/SS1/RPI32/CTED2/RB0
E6	RP113/RG1	K2	PGEC3/CVREF+/OA1OUT/AN3/C1IN4-/C4IN2-/RPI33/ CTED1/RB1
E7	No Connect	К3	VREF+/AN34/PMA7/RF10
K4	OA3OUT/AN6/C3IN4-/C4IN4-/C4IN1+/RP48/OCFB/RC0	L3	AVss
K5	No Connect	L4	OA3IN-/AN7/C3IN1-/C4IN1-/RP49/RC1
K6	AN37/RF12	L5	OA3IN+/AN8/C3IN3-/C3IN1+/RPI50/U1RTS/BCLK1/FLT3/ PMA13/RC2
K7	AN14/RPI94/FLT7/PMA1/RE14	L6	AN36/RF13
K8	VDD	L7	AN13/C3IN2-/U2CTS/FLT6/PMA10/RE13
K9	AN39/RD15	L8	AN15/RPI95/FLT8/PMA0/RE15
K10	OA5IN+/AN24/C5IN3-/C5IN1+/SDO1/RP20/T1CK/RA4	L9	AN38/RD14
K11	AN40/RPI80/RE0	L10	SDA2/RPI24/PMA9/RA8
L1	PGEC1/OA1IN+/AN4/C1IN3-/C1IN1+/C2IN3-/RPI34/RB2	L11	FLT32/SCL2/RP36/PMA8/RB4
12			

TABLE 2:PIN NAMES: dsPIC33EP128/256/512GM310/710 DEVICES^(1,2,3) (CONTINUED)

Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See Section 11.4 "Peripheral Pin Select (PPS)" for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See Section 11.0 "I/O Ports" for more information.

3: The availability of I²C™ interfaces varies by device. Selection (SDAx/SCLx or ASDAx/ASCLx) is made using the device Configuration bits, ALTI2C1 and ALTI2C2 (FPOR<5:4>). See Section 30.0 "Special Features" for more information.

NOTES:





Note 1: Memory areas are not shown to scale.

2: On Reset, these bits are automatically copied into the device Configuration Shadow registers.

4.3 Special Function Register Maps

TABLE 4-1: CPU CORE REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
W0	0000								W0 (WF	REG)								xxxx
W1	0002								W1									xxxx
W2	0004								W2									xxxx
W3	0006								W3									xxxx
W4	8000								W4									xxxx
W5	000A								W5									xxxx
W6	000C								W6									xxxx
W7	000E								W7									xxxx
W8	0010								W8									xxxx
W9	0012								W9									xxxx
W10	0014								W10)								xxxx
W11	0016		W11 xxx									xxxx						
W12	0018		W12 xxxx															
W13	001A		W13 xxxx															
W14	001C		W14 xxx									xxxx						
W15	001E		W15 x2								xxxx							
SPLIM	0020								SPLI	М								0000
ACCAL	0022								ACCA	AL.								0000
ACCAH	0024								ACCA	λH								0000
ACCAU	0026			Si	gn Extensio	n of ACCA<	:39>						AC	CAU				0000
ACCBL	0028								ACCE	BL								0000
ACCBH	002A								ACCE	зн								0000
ACCBU	002C			Si	gn Extensio	n of ACCB<	:39>						AC	CBU				0000
PCL	002E		_				Pr	ogram Cour	nter Low Wo	ord Register	_						—	0000
PCH	0030	_	—	—	—	_	_	_	_	_		Pr	ogram Co	unter High V	Vord Regist	er		0000
DSRPAG	0032	_	_	_	_	_	_				Data S	pace Read	l Page Reg	gister				0001
DSWPAG	0034	_	_	_	_	_	_	_			[Data Space	Write Pag	ge Register				0001
RCOUNT	0036							REPH	EAT LOOP CO	ount Registe	er							0000
DCOUNT	0038								DCOUNT	<15:0>								0000
DOSTARTL	003A							DOS	TARTL<15:	1>							—	0000
DOSTARTH	003C	—									0000							
DOENDL	003E							DO	ENDL<15:1	>		-					—	0000
DOENDH	0040			_										DOEND	0H<5:0>			0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

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	-22.				ILC001													
SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
ADC2BUF9	0352								ADC2 Da	ata Buffer	9							xxxx
ADC2BUFA	0354								ADC2 Da	ta Buffer 1	10							xxxx
ADC2BUFB	0356								ADC2 Da	ta Buffer ´	11							xxxx
ADC2BUFC	0358								ADC2 Da	ta Buffer 1	12							xxxx
ADC2BUFD	035A								ADC2 Da	ta Buffer 1	13							xxxx
ADC2BUFE	035C	ADC2 Data Buffer 14 xxxx																
ADC2BUFF	035E								ADC2 Da	ta Buffer 1	15							xxxx
AD2CON1	0360	ADON	_	ADSIDL	ADDMABM	_	AD12B	FORM1	FORM0	SSRC2	SSRC1	SSRC0	SSRCG	SIMSAM	ASAM	SAMP	DONE	0000
AD2CON2	0362	VCFG2	VCFG1	VCFG0	OFFCAL	_	CSCNA	CHPS1	CHPS0	BUFS	SMPI4	SMPI3	SMPI2	SMPI1	SMPI0	BUFM	ALTS	0000
AD2CON3	0364	ADRC	_	_	SAMC4	SAMC3	SAMC2	SAMC1	SAMC0	ADCS7	ADCS6	ADCS5	ADCS4	ADCS3	ADCS2	ADCS1	ADCS0	0000
AD2CHS123	0366			—	CH123SB2	CH123SB1	CH123NB1	CH123NB0	CH123SB0	-	-	—	CH123SA2	CH123SA1	CH123NA1	CH123NA0	CH123SA0	0000
AD2CHS0	0368	CH0NB	_	CH0SB5 ⁽¹⁾	CH0SB4	CH0SB3	CH0SB2	CH0SB1	CH0SB0	CH0NA		CH0SA5(1)	CH0SA4	CH0SA3	CH0SA2	CH0SA1	CH0SA0	0000
AD2CSSH	036E								CSS<	:31:16>								0000
AD2CSSL	0370								CSS	<15:0>								0000
AD2CON4	0372	_	_		—	_		_	ADDMAEN	_	_	_	_		DMABL2	DMABL1	DMABL0	0000

TABLE 4-22: ADC1 AND ADC2 REGISTER MAP (CONTINUED)

Legend: x = unknown value on Reset; - = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: Bits 13 and bit 5 are reserved in the AD2CHS0 register, unlike the AD1CHS0 register.

REGISTER 6-1: RCON: RESET CONTROL REGISTER⁽¹⁾ (CONTINUED)

 bit 3
 SLEEP: Wake-up from Sleep Flag bit

 1 = Device was in Sleep mode

 0 = Device was not in Sleep mode

 bit 2
 IDLE: Wake-up from Idle Flag bit

 1 = Device was in Idle mode

 0 = Device was not in Idle mode

 0 = Device was not in Idle mode

 bit 1
 BOR: Brown-out Reset Flag bit

 1 = A Brown-out Reset has occurred

 0 = A Brown-out Reset has not occurred

bit 0 **POR:** Power-on Reset Flag bit

- 1 = A Power-on Reset has occurred
- 0 = A Power-on Reset has not occurred
- **Note 1:** All of the Reset status bits can be set or cleared in software. Setting one of these bits in software does not cause a device Reset.
 - 2: If the FWDTEN Configuration bit is '1' (unprogrammed), the WDT is always enabled, regardless of the SWDTEN bit setting.

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0					
—	—	—	—	—	—	—	—					
bit 15							bit 8					
U-0	U-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0					
	—	DAE	DOOVR	—	—	_	—					
bit 7							bit 0					
Legend:												
R = Readabl	le bit	W = Writable	bit	U = Unimple	mented bit, read	as '0'						
-n = Value at	t POR	'1' = Bit is set	t	'0' = Bit is cle	eared	x = Bit is unknown						
bit 15-6	Unimplemen	ted: Read as	'0'									
bit 5	DAE: DMA A	ddress Error S	Soft Trap Status	s bit								
	1 = DMA add	1 = DMA address error soft trap has occurred										
	0 = DMA add	ress error soft	trap has not o	ccurred								
bit 4	DOOVR: DO	Stack Overflow	v Soft Trap Sta	tus bit								
	1 = DO stack	1 = DO stack overflow soft trap has occurred										

REGISTER 7-5: INTCON3: INTERRUPT CONTROL REGISTER 3

	0 = DO stack overflow soft trap has not occurred
bit 3-0	Unimplemented: Read as '0'

REGISTER 7-6: INTCON4: INTERRUPT CONTROL REGISTER 4

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15			•				bit 8
U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	SGHT
bit 7							bit 0
Legend:							

R = Readable bitW = Writable bitU = Unimplemented bit, read as '0'-n = Value at POR'1' = Bit is set'0' = Bit is clearedx = Bit is unknown	Legena.			
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown	R = Readable bit	W = Writable bit	U = Unimplemented bit, read	as '0'
	-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 0 SGHT: Software Generated Hard Trap Status bit

- 1 = Software generated hard trap has occurred
- 0 = Software generated hard trap has not occurred

REGISTER 11-20. RFINR40. FERIFIERAL FIN SELECT INFUT REGISTER 40	REGISTER 11-28:	RPINR40: PERIPHERAL PIN SELECT INPUT REGISTER 40
--	-----------------	---

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0					
_				DTCMP5R<6:0)>							
bit 15							bit 8					
U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0					
_				DTCMP4R<6:)>							
bit 7							bit 0					
Legend:												
R = Readabl	e bit	W = Writable	bit	ad as '0'								
-n = Value at	POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkr	nown					
bit 15	Unimpleme	nted: Read as '	0'									
bit 14-8	DTCMP5R< (see Table 1 ²	5:0>: Assign PV I-2 for input pin	VM Dead-Tim selection nur	e Compensation nbers)	on Input 5 to th	e Corresponding	g RPn Pin bits					
	1111100 = 	nput tied to RPI	124									
	•											
	•											
	0000001 = 	nput tied to CM	P1									
	0000000 = I	nput tied to Vss										
bit 7	Unimpleme	nted: Read as '	0'									
bit 6-0		DTCMP4R<6:0>: Assign PWM Dead-Time Compensation Input 4 to the Corresponding RPn Pin bits										
		(see Table 11-2 for input pin selection numbers)										
	•		124									
	•											
	•											
	0000001 = 0000000 =	nput tied to CM nput tied to Vss	P1									

REGISTER 15-1: OCxCON1: OUTPUT COMPARE x CONTROL REGISTER 1 (CONTINUED)

- bit 3 TRIGMODE: Trigger Status Mode Select bit
 - 1 = TRIGSTAT (OCxCON2<6>) is cleared when OCxRS = OCxTMR or in software
 - 0 = TRIGSTAT is cleared only by software

bit 2-0 OCM<2:0>: Output Compare x Mode Select bits

- 111 = Center-Aligned PWM mode: Output sets high when OCxTMR = OCxR and sets low when OCxTMR = OCxRS⁽¹⁾
- 110 = Edge-Aligned PWM mode: Output sets high when OCxTMR = 0 and sets low when OCxTMR = OCxR⁽¹⁾
- 101 = Double Compare Continuous Pulse mode: Initializes OCx pin low, toggles OCx state continuously on alternate matches of OCxR and OCxRS
- 100 = Double Compare Single-Shot mode: Initializes OCx pin low, toggles OCx state on matches of OCxR and OCxRS for one cycle
- 011 = Single Compare mode: Compare event with OCxR, continuously toggles OCx pin
- 010 = Single Compare Single-Shot mode: Initializes OCx pin high, compare event with OCxR, forces OCx pin low
- 001 = Single Compare Single-Shot mode: Initializes OCx pin low, compare event with OCxR, forces OCx pin high
- 000 = Output compare channel is disabled
- **Note 1:** OCxR and OCxRS are double-buffered in PWM mode only.
 - 2: Each Output Compare x module (OCx) has one PTG clock source. See Section 25.0 "Peripheral Trigger Generator (PTG) Module" for more information.
 - PTGO4 = OC1, OC5
 - PTGO5 = OC2, OC6
 - PTGO6 = OC3, OC7
 - PTGO7 = OC4, OC8

17.0 QUADRATURE ENCODER INTERFACE (QEI) MODULE

- Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGM3XX/6XX/7XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the "dsPIC33/PIC24 Family Reference Manual", "Quadrature Encoder Interface (QEI)" (DS70601) which is available from the Microchip web site (www.microchip.com).
 - 2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

This chapter describes the Quadrature Encoder Interface (QEI) module and associated operational modes. The QEI module provides the interface to incremental encoders for obtaining mechanical position data.

The operational features of the QEI module include:

- · 32-Bit Position Counter
- 32-Bit Index Pulse Counter
- 32-Bit Interval Timer
- 16-Bit Velocity Counter
- 32-Bit Position Initialization/Capture/Compare High Register
- 32-Bit Position Compare Low Register
- x4 Quadrature Count mode
- External Up/Down Count mode
- External Gated Count mode
- · External Gated Timer mode
- Internal Timer mode

Figure 17-1 illustrates the QEIx block diagram.

REGISTER 18-1: SPIx STAT: SPIx STATUS AND CONTROL REGISTER (CONTINUED)

bit 1 SPITBF: SPIx Transmit Buffer Full Status bit

1 = Transmit has not yet started, SPIxTXB is full

0 = Transmit has started, SPIxTXB is empty

Standard Buffer Mode:

Automatically set in hardware when the core writes to the SPIxBUF location, loading SPIxTXB. Automatically cleared in hardware when the SPIx module transfers data from SPIxTXB to SPIxSR.

Enhanced Buffer Mode:

Automatically set in hardware when the CPU writes to the SPIxBUF location, loading the last available buffer location. Automatically cleared in hardware when a buffer location is available for a CPU write operation.

bit 0 SPIRBF: SPIx Receive Buffer Full Status bit

1 = Receive is complete, SPIxRXB is full

0 = Receive is incomplete, SPIxRXB is empty

Standard Buffer Mode:

Automatically set in hardware when SPIx transfers data from SPIxSR to SPIxRXB. Automatically cleared in hardware when the core reads the SPIxBUF location, reading SPIxRXB.

Enhanced Buffer Mode:

Automatically set in hardware when SPIx transfers data from SPIxSR to the buffer, filling the last unread buffer location. Automatically cleared in hardware when a buffer location is available for a transfer from SPIxSR.

R/W-0	R/W-0	R/W-0	R/W-0	U	-0	R/W-0	R/W-0	R/W-0		
VCFG2 ⁽¹⁾	VCFG1	¹⁾ VCFG0 ⁽¹⁾	OFFCAL	_	_	CSCNA	CHPS1	CHPS0		
bit 15								bit 8		
R-0	R/W-0	R/W-0	R/W-0	R/V	V-0	R/W-0	R/W-0	R/W-0		
BUFS	SMPI4	SMPI3	SMPI2	SM	PI1	SMPI0	BUFM	ALTS		
bit 7								bit 0		
Legend:										
R = Readable	bit	W = Writable bi	t	U = UI	nimpler	mented bit, rea	d as '0'			
-n = Value at POR		'1' = Bit is set	'1' = Bit is set			ared	x = Bit is unk	x = Bit is unknown		
bit 15-13	VCFG<2:	0>: Converter Voltag	e Reference	Configu	uration	bits ⁽¹⁾				
	Value	VREFH	VREFL	-						
	000	Avdd	Avss							
	001	External VREF+(2)	Avss							
	010	Avdd	External VR	REF- (2)						
	011	External VREF+(2)	External VR	_{REF-} (2)						
	1xx	Avdd	Avss							
bit 12	OFFCAL:	Offset Calibration N	lode Select b	it						

REGISTER 23-2: ADxCON2: ADCx CONTROL REGISTER 2

1 = + and - inputs of channel Sample-and-Hold are connected to AVss

0 = + and – inputs of channel Sample-and-Hold are normal

- bit 11 Unimplemented: Read as '0'
- bit 10 CSCNA: Input Scan Select bit
 - 1 = Scans inputs for CH0+ during Sample MUXA

0 = Does not scan inputs

bit 9-8 CHPS<1:0>: Channel Select bits

In 12-Bit Mode (AD12B = 1), CHPS<1:0> Bits are Unimplemented and are Read as '00':

- lx = Converts CH0, CH1, CH2 and CH3
- 01 = Converts CH0 and CH1
- 00 = Converts CH0
- bit 7 **BUFS:** Buffer Fill Status bit (only valid when BUFM = 1)
 - 1 = ADCx is currently filling the second half of the buffer; the user application should access data in the first half of the buffer
 - 0 = ADCx is currently filling the first half of the buffer; the user application should access data in the second half of the buffer
- **Note 1:** The '001', '010' and '011' bit combinations for VCFG<2:0> are not applicable on ADC2.
 - 2: ADC2 does not support external VREF± inputs.



FIGURE 26-2: OP AMP/COMPARATOR VOLTAGE REFERENCE BLOCK DIAGRAM

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	
PTEN15	PTEN14			PTEN	<13:8>			
bit 15							bit 8	
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	
		PTEN	 <7:2>			PTEN	I <1:0>	
bit 7							bit 0	
Legend:								
R = Readab	ole bit	W = Writable	bit	U = Unimplen	nented bit, rea	d as '0'		
-n = Value at Reset		'1' = Bit is set '0' =		'0' = Bit is clea	0' = Bit is cleared		x = Bit is unknown	
bit 15	PTEN15: PM	1CS2 Strobe En	able bit					
	1 = PMA15 f	unctions as eith	er PMA<15> c	or PMCS2				
	0 = PMA15 f	unctions as port	t I/O					
bit 14	PTEN14: PM	ICS1 Strobe En	able bit					
	1 = PMA14 f	unctions as eith	er PMA<14> c	or PMCS1				
	0 = PMA14 f	unctions as port	t I/O					
bit 13-2	PTEN<13:2>	PMP Address	Port Enable b	oits				
	1 = PMA<13 0 = PMA<13	:2> function as :2> function as	PMP address port I/Os	lines				
bit 1-0	PTEN<1:0>:	PMALH/PMALI	L Strobe Enabl	le bits				

1 = PMA1 and PMA0 function as either PMA<1:0> or PMALH and PMALL

REGISTER 28-4: PMAEN: PARALLEL MASTER PORT ADDRESS ENABLE REGISTER⁽¹⁾

Note 1: This register is not available on 44-pin devices.

0 = PMA1 and PMA0 function as port I/Os

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Base Instr #	Assembly Mnemonic		Assembly Syntax	Description	# of Words	# of Cycles	Status Flags Affected
53	NEG	NEG	Acc	Negate Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
		NEG	f	f = f + 1	1	1	C,DC,N,OV,Z
		NEG	f,WREG	WREG = \overline{f} + 1	1	1	C,DC,N,OV,Z
		NEG	Ws,Wd	$Wd = \overline{Ws} + 1$	1	1	C,DC,N,OV,Z
54	NOP	NOP		No Operation	1	1	None
		NOPR		No Operation	1	1	None
55	POP	POP	f	Pop f from Top-of-Stack (TOS)	1	1	None
		POP	Wdo	Pop from Top-of-Stack (TOS) to Wdo	1	1	None
		POP.D	Wnd	Pop from Top-of-Stack (TOS) to W(nd):W(nd + 1)	1	2	None
		POP.S		Pop Shadow Registers	1	1	All
56	PUSH	PUSH	f	Push f to Top-of-Stack (TOS)	1	1	None
		PUSH	Wso	Push Wso to Top-of-Stack (TOS)	1	1	None
		PUSH.D	Wns	Push W(ns):W(ns + 1) to Top-of-Stack (TOS)	1	2	None
		PUSH.S		Push Shadow Registers	1	1	None
57	PWRSAV	PWRSAV	#lit1	Go into Sleep or Idle mode	1	1	WDTO,Sleep
58	RCALL	RCALL	Expr	Relative Call	1	4	SFA
		RCALL	Wn	Computed Call	1	4	SFA
59	REPEAT	REPEAT	#lit15	Repeat Next Instruction lit15 + 1 times	1	1	None
		REPEAT	Wn	Repeat Next Instruction (Wn) + 1 times	1	1	None
60	RESET	RESET		Software device Reset	1	1	None
61	RETFIE	RETFIE		Return from interrupt	1	6 (5)	SFA
62	RETLW	RETLW	#lit10,Wn	Return with literal in Wn	1	6 (5)	SFA
63	RETURN	RETURN		Return from Subroutine	1	6 (5)	SFA
64	RLC	RLC	f	f = Rotate Left through Carry f	1	1	C,N,Z
		RLC	f,WREG	WREG = Rotate Left through Carry f	1	1	C,N,Z
		RLC	Ws,Wd	Wd = Rotate Left through Carry Ws	1	1	C,N,Z
65	RLNC	RLNC	f	f = Rotate Left (No Carry) f	1	1	N,Z
		RLNC	f,WREG	WREG = Rotate Left (No Carry) f	1	1	N,Z
		RLNC	Ws,Wd	VVd = Rotate Left (No Carry) VVs	1	1	N,Z
60	RRC	RRC	I CARDO	T = Rotate Right through Carry f	1	1	C,N,Z
		RRC	L, WREG	WREG - Rotate Right through Carry Wa	1	1	
67	DDNC	RRC	ws,wa	f = Rotate Right (No Carry) f	1	1	0,N,Z
07	KKINC	PRNC	L f WDTC	W/REG = Potate Pight (No Carry) f	1	1	N Z
		PRNC	Ne Wd	Wd = Rotate Right (No Carry) Ws	1	1	N Z
68	SAC	SAC	Acc #Slit4 Wdo	Store Accumulator	1	1	None
00	brie	SAC R	Acc. #Slit4.Wdo	Store Rounded Accumulator	1	1	None
69	SE	SE	Ws.Wnd	Wnd = sign-extended Ws	1	1	C.N.Z
70	SETM	SETM	f	f = 0xFFFF	1	1	None
		SETM	WREG	WREG = 0xFFFF	1	1	None
		SETM	Ws	Ws = 0xFFFF	1	1	None
71	SFTAC	SFTAC	Acc,Wn	Arithmetic Shift Accumulator by (Wn)	1	1	OA,OB,OAB, SA,SB.SAB
		SFTAC	Acc,#Slit6	Arithmetic Shift Accumulator by Slit6	1	1	OA,OB,OAB, SA,SB,SAB

TABLE 31-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Note: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V(unless otherwise stated)Operating temperature $-40^{\circ}C \le TA \le +85^{\circ}C$ for Industrial $-40^{\circ}C \le TA \le +125^{\circ}C$ for Extended					
Param No.	Symbol	Characteristic	Min. Typ. Max. Units Conditions					
	lı∟	Input Leakage Current ^(1,2)						
D150		I/O Pins 5V Tolerant ⁽³⁾	-1	—	+1	μA	VSS \leq VPIN \leq 5V, Pin at high-impedance	
DI51		I/O Pins Not 5V Tolerant ⁽³⁾	-1	_	+1	μA	$\label{eq:VSS} \begin{array}{l} VSS \leq VPIN \leq VDD, \\ Pin \text{ at high-impedance}, \\ -40^\circC \leq TA \leq +85^\circC \end{array}$	
DI51a		I/O Pins Not 5V Tolerant ⁽³⁾	-1	_	+1	μA	Analog pins shared with external reference pins, $-40^{\circ}C \le TA \le +85^{\circ}C$	
DI51b		I/O Pins Not 5V Tolerant ⁽³⁾	-1	_	+1	μA	Vss \leq VPIN \leq VDD, Pin at high-impedance, -40°C \leq TA \leq +125°C	
DI51c		I/O Pins Not 5V Tolerant ⁽³⁾	-1	_	+1	μA	Analog pins shared with external reference pins, $-40^{\circ}C \le TA \le +125^{\circ}C$	
DI55		MCLR	-5	—	+5	μA	$Vss \leq V \text{PIN} \leq V \text{DD}$	
DI56		OSC1	-5	_	+5	μA	$\label{eq:VSS} \begin{array}{l} VSS \leq VPIN \leq VDD, \\ XT \text{ and } HS \text{ modes} \end{array}$	

TABLE 33-10: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

Note 1: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.

- 2: Negative current is defined as current sourced by the pin.
- 3: See the "Pin Diagrams" section for the 5V tolerant I/O pins.
- 4: VIL source < (Vss 0.3). Characterized but not tested.
- **5:** Non-5V tolerant pins VIH source > (VDD + 0.3), 5V tolerant pins VIH source > 5.5V. Characterized but not tested.
- 6: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5.5V.
- 7: Non-zero injection currents can affect the ADC results by approximately 4-6 counts.

8: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

TABLE 33-40: SPI1 MAXIMUM DATA/CLOCK RATE SUMMAR)	TABLE 33-40:	SPI1 MAXIMUM DATA/CLOCK RATE SUMMARY
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AC CHARACTERISTICS			$\begin{tabular}{lllllllllllllllllllllllllllllllllll$				
Maximum Data Rate	Master Transmit Only (Half-Duplex)	Master Transmit/Receive (Full-Duplex)	Slave Transmit/Receive (Full-Duplex)	CKE	СКР	SMP	
25 MHz	Table 33-41	—	_	0,1	0,1	0,1	
25 MHz	—	Table 33-42	_	1	0,1	1	
25 MHz	—	Table 33-43		0	0,1	1	
25 MHz	—	—	Table 33-44	1	0	0	
25 MHz	—	—	Table 33-45	1	1	0	
25 MHz	_	_	Table 33-46	0	1	0	
25 MHz	_	_	Table 33-47	0	0	0	

FIGURE 33-23: SPI1 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 0) TIMING CHARACTERISTICS



TABLE	33-60:	ADCx CONVERSION (10-BIT M	ODE) TI	MING R	EQUIRE	MENTS	
АС СН	ARACTE	RISTICS	Standar (unless Operation	rd Operat otherwis	ing Conc se stated) ature -4	litions (s) ł0°C ≤ Ta ł0°C ≤ Ta	ee Note 1): 3.0V to 3.6V ≤ +85°C for Industrial ≤ +125°C for Extended
Param No.	Symbol	Characteristic	Min.	Тур. ⁽⁴⁾	Max.	Units	Conditions
		Cloc	k Parame	eters			
AD50	TAD	ADCx Clock Period	75	_	_	ns	
AD51	tRC	ADCx Internal RC Oscillator Period	—	250	_	ns	
		Con	version F	Rate			
AD55	tCONV	Conversion Time	—	12 Tad	_	—	
AD56	FCNV	Throughput Rate	—	—	1.1	Msps	Using simultaneous sampling
AD57a	TSAMP	Sample Time When Sampling Any ANx Input	2 Tad	—		_	
AD57b	TSAMP	Sample Time When Sampling the Op Amp Outputs	4 Tad	—		_	
		Timin	g Param	eters			
AD60	tPCS	Conversion Start from Sample Trigger ⁽²⁾	2 Tad	_	3 Tad	_	Auto-convert trigger not selected
AD61	tPSS	Sample Start from Setting Sample (SAMP) bit ⁽²⁾	2 Tad	—	3 Tad	_	
AD62	tcss	Conversion Completion to Sample Start (ASAM = 1) ⁽²⁾		0.5 TAD		-	
AD63	t DPU	Time to Stabilize Analog Stage			20	μS	(Note 3)

Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality Note 1: is tested, but not characterized. Analog modules: ADC, op amp/comparator and comparator voltage reference, will have degraded performance. Refer to Parameter BO10 in Table 33-12 for the minimum and maximum BOR values.

2: Because the sample caps will eventually lose charge, clock rates below 10 kHz may affect linearity performance, especially at elevated temperatures.

3: The parameter, tDPU, is the time required for the ADCx module to stabilize at the appropriate level when the module is turned on (AD1CON1<ADON> = 1). During this time, the ADCx result is indeterminate.

4: These parameters are characterized, but not tested in manufacturing.

from ADC Off to ADC On⁽²⁾

64-Lead Plastic Thin Quad Flatpack (PT) 10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	MILLIMETERS				
Dimensio	MIN	NOM	MAX		
Contact Pitch	E		0.50 BSC		
Contact Pad Spacing	C1		11.40		
Contact Pad Spacing	C2		11.40		
Contact Pad Width (X64)	X1			0.30	
Contact Pad Length (X64)	Y1			1.50	
Distance Between Pads	G	0.20			

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2085B

121-Ball Plastic Thin Profile Fine Pitch Ball Grid Array (BG) - 10x10x1.10 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-148 Rev F Sheet 1 of 2